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Details

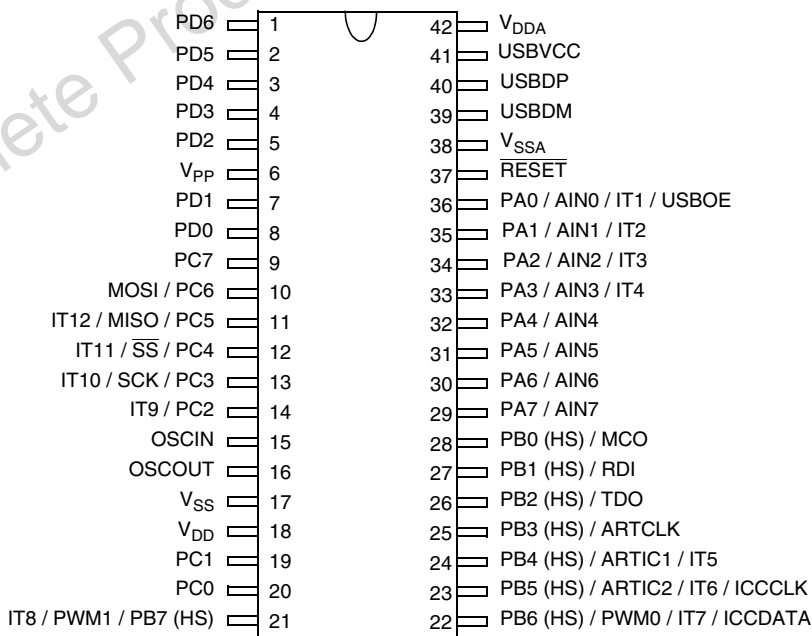
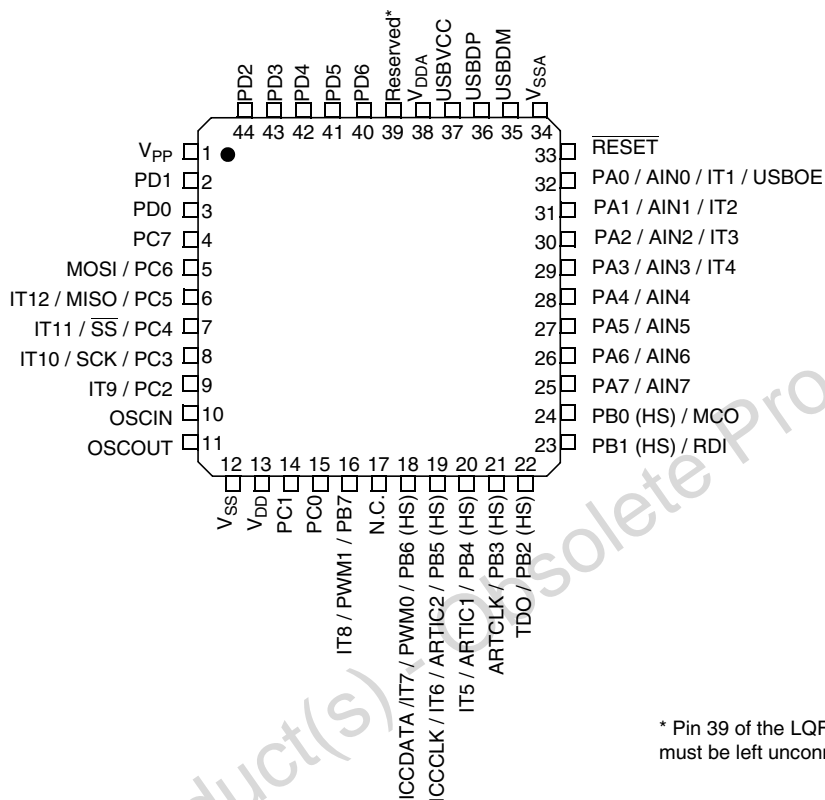
Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	11
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	384 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 3x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SO
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f623f2m1tr

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2 PIN DESCRIPTION

Figure 2. 44-pin LQFP and 42-Pin SDIP Package Pinouts



FLASH PROGRAM MEMORY (Cont'd)

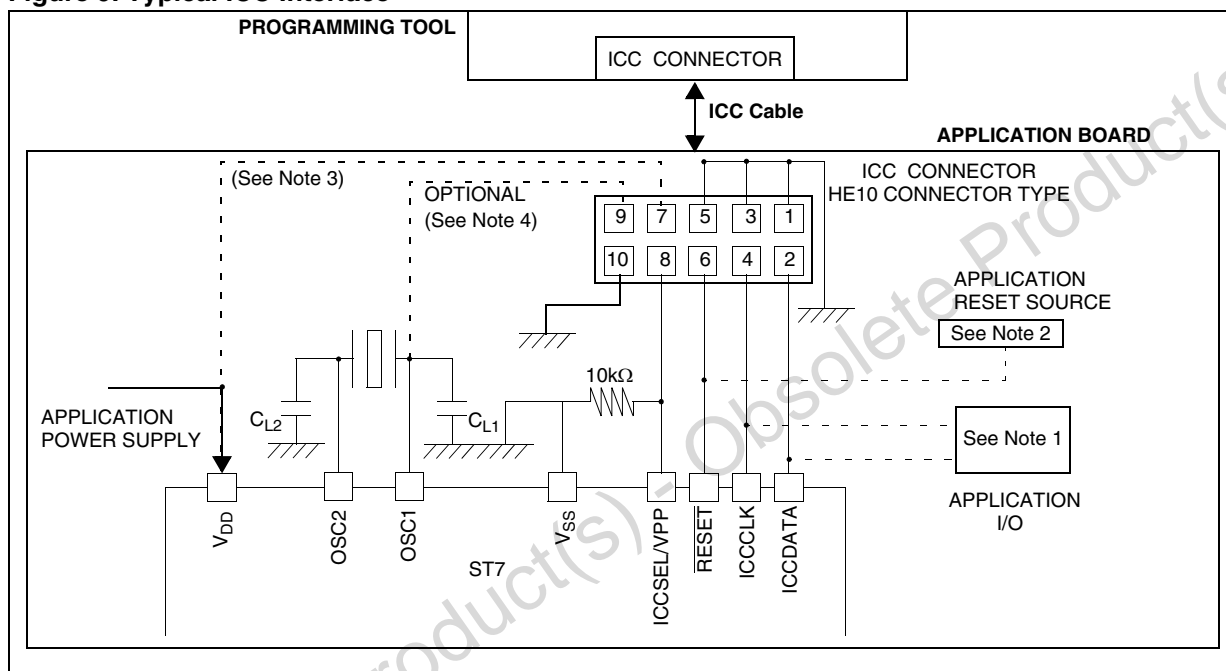
4.4 ICC INTERFACE

ICC (In-Circuit Communication) needs a minimum of four and up to six pins to be connected to the programming tool (see Figure 9). These pins are:

- RESET: device reset
- V_{SS}: device power supply ground

- ICCCLK: ICC output serial clock pin
- ICCDATA: ICC input/output serial data pin
- ICCSEL/V_{PP}: programming voltage
- OSC1(or OSCIN): main clock input for external source (optional)
- V_{DD}: application board power supply (see Figure 9, Note 3)

Figure 9. Typical ICC Interface



Notes:

1. If the ICCCLK or ICCDATA pins are only used as outputs in the application, no signal isolation is necessary. As soon as the Programming Tool is plugged to the board, even if an ICC session is not in progress, the ICCCLK and ICCDATA pins are not available for the application. If they are used as inputs by the application, isolation such as a serial resistor has to be implemented in case another device forces the signal. Refer to the Programming Tool documentation for recommended resistor values.

2. During the ICC session, the programming tool must control the RESET pin. This can lead to conflicts between the programming tool and the application reset circuit if it drives more than 5mA at high level (push pull output or pull-up resistor < 1K). A schottky diode can be used to isolate the application RESET circuit in this case. When using a classical RC network with R > 1K or a reset man-

agement IC with open drain output and pull-up resistor > 1K, no additional components are needed. In all cases the user must ensure that no external reset is generated by the application during the ICC session.

3. The use of Pin 7 of the ICC connector depends on the Programming Tool architecture. This pin must be connected when using most ST Programming Tools (it is used to monitor the application power supply). Please refer to the Programming Tool manual.

4. Pin 9 has to be connected to the OSC1 or OSCIN pin of the ST7 when the clock is not available in the application or if the selected clock option is not programmed in the option byte. ST7 devices with multioscillator capability need to have OSC2 grounded in this case.

FLASH PROGRAM MEMORY (Cont'd)

4.5 ICP (IN-CIRCUIT PROGRAMMING)

To perform ICP the microcontroller must be switched to ICC (In-Circuit Communication) mode by an external controller or programming tool.

Depending on the ICP code downloaded in RAM, Flash memory programming can be fully customized (number of bytes to program, program locations, or selection serial communication interface for downloading).

When using an STMicroelectronics or third-party programming tool that supports ICP and the specific microcontroller device, the user needs only to implement the ICP hardware interface on the application board (see [Figure 9](#)). For more details on the pin locations, refer to the device pinout description.

4.6 IAP (IN-APPLICATION PROGRAMMING)

This mode uses a BootLoader program previously stored in Sector 0 by the user (in ICP mode or by plugging the device in a programming tool).

This mode is fully controlled by user software. This allows it to be adapted to the user application, (user-defined strategy for entering programming mode, choice of communications protocol used to fetch the data to be stored, etc.). For example, it is possible to download code from the SPI, SCI or other type of serial interface and program it in the Flash. IAP mode can be used to program any of the Flash sectors except Sector 0, which is write/erase protected to allow recovery in case errors occur during the programming operation.

4.7 RELATED DOCUMENTATION

For details on Flash programming and ICC protocol, refer to the *ST7 Flash Programming Reference Manual* and to the *ST7 ICC Protocol Reference Manual*.

4.8 REGISTER DESCRIPTION

FLASH CONTROL/STATUS REGISTER (FCSR)

Read/Write
Reset Value: 0000 0000 (00h)

7				0			
0	0	0	0	0	0	0	0

This register is reserved for use by Programming Tool software. It controls the Flash programming and erasing operations.



CENTRAL PROCESSING UNIT (Cont'd)**Condition Code Register (CC)**

Read/Write

Reset Value: 111x1xxx

7							0
1	1	I1	H	I0	N	Z	C

The 8-bit Condition Code register contains the interrupt masks and four flags representative of the result of the instruction just executed. This register can also be handled by the PUSH and POP instructions.

These bits can be individually tested and/or controlled by specific instructions.

Arithmetic Management BitsBit 4 = **H** *Half carry*.

This bit is set by hardware when a carry occurs between bits 3 and 4 of the ALU during an ADD or ADC instructions. It is reset by hardware during the same instructions.

0: No half carry has occurred.

1: A half carry has occurred.

This bit is tested using the JRH or JRNH instruction. The H bit is useful in BCD arithmetic subroutines.

Bit 2 = **N** *Negative*.

This bit is set and cleared by hardware. It is representative of the result sign of the last arithmetic, logical or data manipulation. It's a copy of the result 7th bit.

0: The result of the last operation is positive or null.

1: The result of the last operation is negative (i.e. the most significant bit is a logic 1).

This bit is accessed by the JRMI and JRPL instructions.

Bit 1 = **Z** *Zero*.

This bit is set and cleared by hardware. This bit indicates that the result of the last arithmetic, logical or data manipulation is zero.

0: The result of the last operation is different from zero.

1: The result of the last operation is zero.

This bit is accessed by the JREQ and JRNE test instructions.

Bit 0 = **C** *Carry/borrow*.

This bit is set and cleared by hardware and software. It indicates an overflow or an underflow has occurred during the last arithmetic operation.

0: No overflow or underflow has occurred.

1: An overflow or underflow has occurred.

This bit is driven by the SCF and RCF instructions and tested by the JRC and JRNC instructions. It is also affected by the "bit test and branch", shift and rotate instructions.

Interrupt Management BitsBit 5,3 = **I1, I0** *Interrupt*

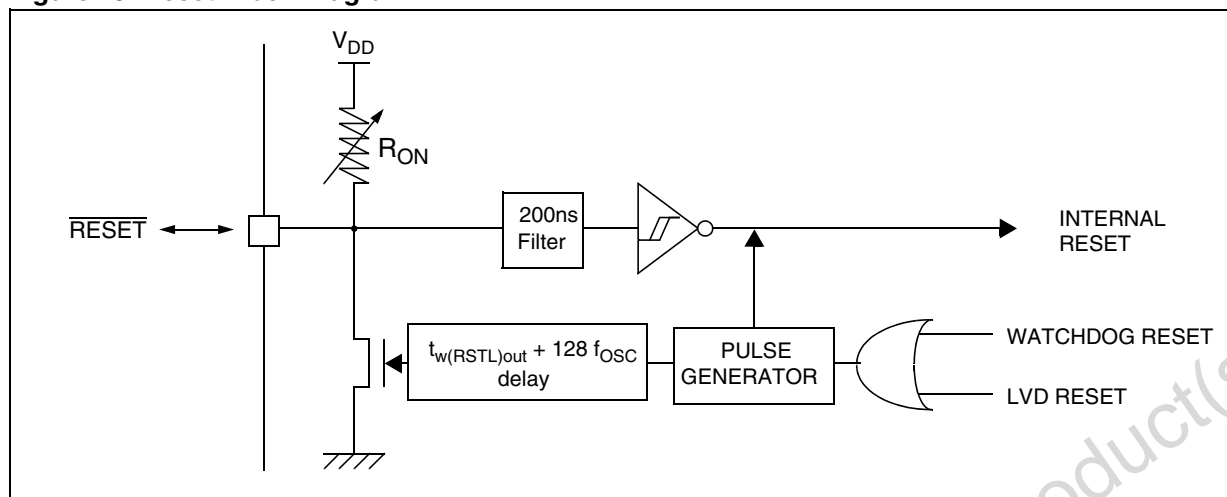
The combination of the I1 and I0 bits gives the current interrupt software priority.

Interrupt Software Priority	I1	I0
Level 0 (main)	1	0
Level 1	0	1
Level 2	0	0
Level 3 (= interrupt disable)	1	1

These two bits are set/cleared by hardware when entering in interrupt. The loaded value is given by the corresponding bits in the interrupt software priority registers (IxSPR). They can be also set/cleared by software with the RIM, SIM, IRET, HALT, WFI and PUSH/POP instructions.

See the interrupt management chapter for more details.

Figure 19. Reset Block Diagram



Note: The output of the external reset circuit must have an open-drain output to drive the ST7 reset pad. Otherwise the device can be damaged when the ST7 generates an internal reset (LVD or watchdog).

INTERRUPTS (Cont'd)**Table 6. Interrupt Mapping**

N°	Source Block	Description	Register Label	Priority Order	Exit from HALT	Address Vector
		Reset		Highest Priority <div>↓</div>	Yes	FFFEh-FFFFh
		TRAP software interrupt			No	FFFCCh-FFFDh
0	ICP	FLASH Start programming NMI interrupt			Yes	FFFAh-FFFBh
1	USB	USB End Suspend interrupt	USBISTR		Yes	FFF8h-FFF9h
2	I/O Ports	Port A external interrupts IT[4:1]	ITRFRE1		Yes	FFF6h-FFF7h
3		Port B external interrupts IT[8:5]	ITRFRE1		Yes	FFF4h-FFF5h
4		Port C external interrupts IT[12:9]	ITRFRE2		Yes	FFF2h-FFF3h
5	TBU	Timebase Unit interrupt	TBUCSR		No	FFF0h-FFF1h
6	ART	ART/PWM Timer interrupt	ICCSR		Yes	FFEEh-FFEFh
7	SPI	SPI interrupt vector	SPISR		Yes	FFECCh-FFEDh
8	SCI	SCI interrupt vector	SCISR	No	FFEAh-FFEBh	
9	USB	USB interrupt vector	USBISTR	Lowest Priority	No	FFE8h-FFE9h
10	ADC	A/D End of conversion interrupt	ADCCSR		No	FFE6h-FFE7h
Reserved area						FFE0h-FFE5h

Table 7. Nested Interrupts Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0032h	ISPR0 Reset Value	Ext. Interrupt Port B		Ext. Interrupt Port A		USB END SUSP		Not Used	
		I1_3 1	I0_3 1	I1_2 1	I0_2 1	I1_1 1	I0_1 1	1	1
0033h	ISPR1 Reset Value	SPI		ART		TBU		Ext. Interrupt Port C	
		I1_7 1	I0_7 1	I1_6 1	I0_6 1	I1_5 1	I0_5 1	I1_4 1	I0_4 1
0034h	ISPR2 Reset Value	Not Used		ADC		USB		SCI	
		I1_11 1	I0_11 1	I1_10 1	I0_10 1	I1_9 1	I0_9 1	I1_8 1	I0_8 1
0035h	ISPR3 Reset Value	1	1	1	1	Not Used		Not Used	
						I1_13 1	I0_13 1	I1_12 1	I0_12 1

9 I/O PORTS

9.1 INTRODUCTION

The I/O ports offer different functional modes: transfer of data through digital inputs and outputs and for specific pins:

- Analog signal input (ADC)
- Alternate signal input/output for the on-chip peripherals.
- External interrupt generation

An I/O port is composed of up to 8 pins. Each pin can be programmed independently as digital input or digital output.

9.2 FUNCTIONAL DESCRIPTION

Each port is associated with 2 main registers:

- Data Register (DR)
- Data Direction Register (DDR)

Each I/O pin may be programmed using the corresponding register bits in DDR register: bit x corresponding to pin x of the port. The same correspondence is used for the DR register.

Table 8. I/O Pin Functions

DDR	MODE
0	Input
1	Output

9.2.1 Input Modes

The input configuration is selected by clearing the corresponding DDR register bit.

In this case, reading the DR register returns the digital value applied to the external I/O pin.

Notes:

1. All the inputs are triggered by a Schmitt trigger.
2. When switching from input mode to output mode, the DR register should be written first to output the correct value as soon as the port is configured as an output.

Interrupt function

When an external interrupt function of an I/O pin, is enabled using the ITFRE registers, an event on this I/O can generate an external Interrupt request to the CPU. The interrupt sensitivity is programma-

ble, the options are given in the description of the ITFRE interrupt registers.

Each pin can independently generate an Interrupt request.

Each external interrupt vector is linked to a dedicated group of I/O port pins (see Interrupts section). If more than one input pin is selected simultaneously as interrupt source, this is logically ANDed and inverted. For this reason, if an event occurs on one of the interrupt pins, it masks the other ones.

9.2.2 Output Mode

The pin is configured in output mode by setting the corresponding DDR register bit (see Table 7).

In this mode, writing “0” or “1” to the DR register applies this digital value to the I/O pin through the latch. Then reading the DR register returns the previously stored value.

Note: In this mode, the interrupt function is disabled.

9.2.3 Alternate Functions

Digital Alternate Functions

When an on-chip peripheral is configured to use a pin, the alternate function is automatically selected. This alternate function takes priority over standard I/O programming. When the signal is coming from an on-chip peripheral, the I/O pin is automatically configured in output mode (push-pull or open drain according to the peripheral).

When the signal is going to an on-chip peripheral, the I/O pin has to be configured in input mode. In this case, the pin state is also digitally readable by addressing the DR register.

Notes:

1. Input pull-up configuration can cause an unexpected value at the alternate peripheral input.
2. When the on-chip peripheral uses a pin as input and output, this pin must be configured as an input (DDR = 0).

Warning: Alternate functions of peripherals must must not be activated when the external interrupts are enabled on the same pin, in order to avoid generating spurious interrupts.

Table 19. SPI Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0011h	SPIDR Reset Value	MSB x	x	x	x	x	x	x	LSB x
0012h	SPICR Reset Value	SPIE 0	SPE 0	SPR2 0	MSTR 0	CPOL x	CPHA x	SPR1 x	SPR0 x
0013h	SPICSR Reset Value	SPIF 0	WCOL 0	OVR 0	MODF 0	0	SOD 0	SSM 0	SSI 0

SERIAL COMMUNICATIONS INTERFACE (Cont'd)**10.5.4 Functional Description**

The block diagram of the Serial Control Interface, is shown in [Figure 46](#). It contains six dedicated registers:

- Two control registers (SCICR1 & SCICR2)
- A status register (SCISR)
- A baud rate register (SCIBRR)
- An extended prescaler receiver register (SCIERR)
- An extended prescaler transmitter register (SCIETPR)

Refer to the register descriptions in [Section 10.5.7](#) for the definitions of each bit.

10.5.4.1 Serial Data Format

Word length may be selected as being either 8 or 9 bits by programming the M bit in the SCICR1 register (see [Figure 46](#)).

The TDO pin is in low state during the start bit.

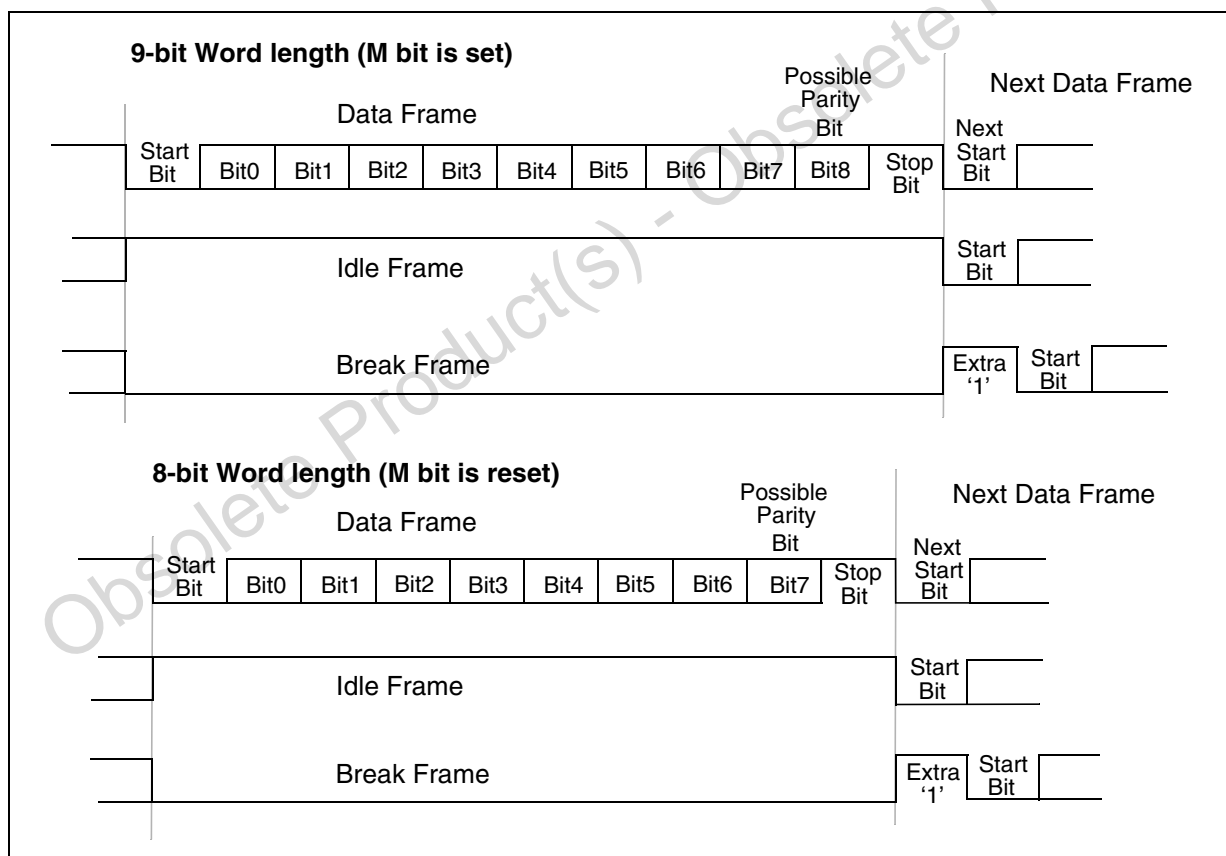
The TDO pin is in high state during the stop bit.

An Idle character is interpreted as an entire frame of “1”s followed by the start bit of the next frame which contains data.

A Break character is interpreted on receiving “0”s for some multiple of the frame period. At the end of the last break frame the transmitter inserts an extra “1” bit to acknowledge the start bit.

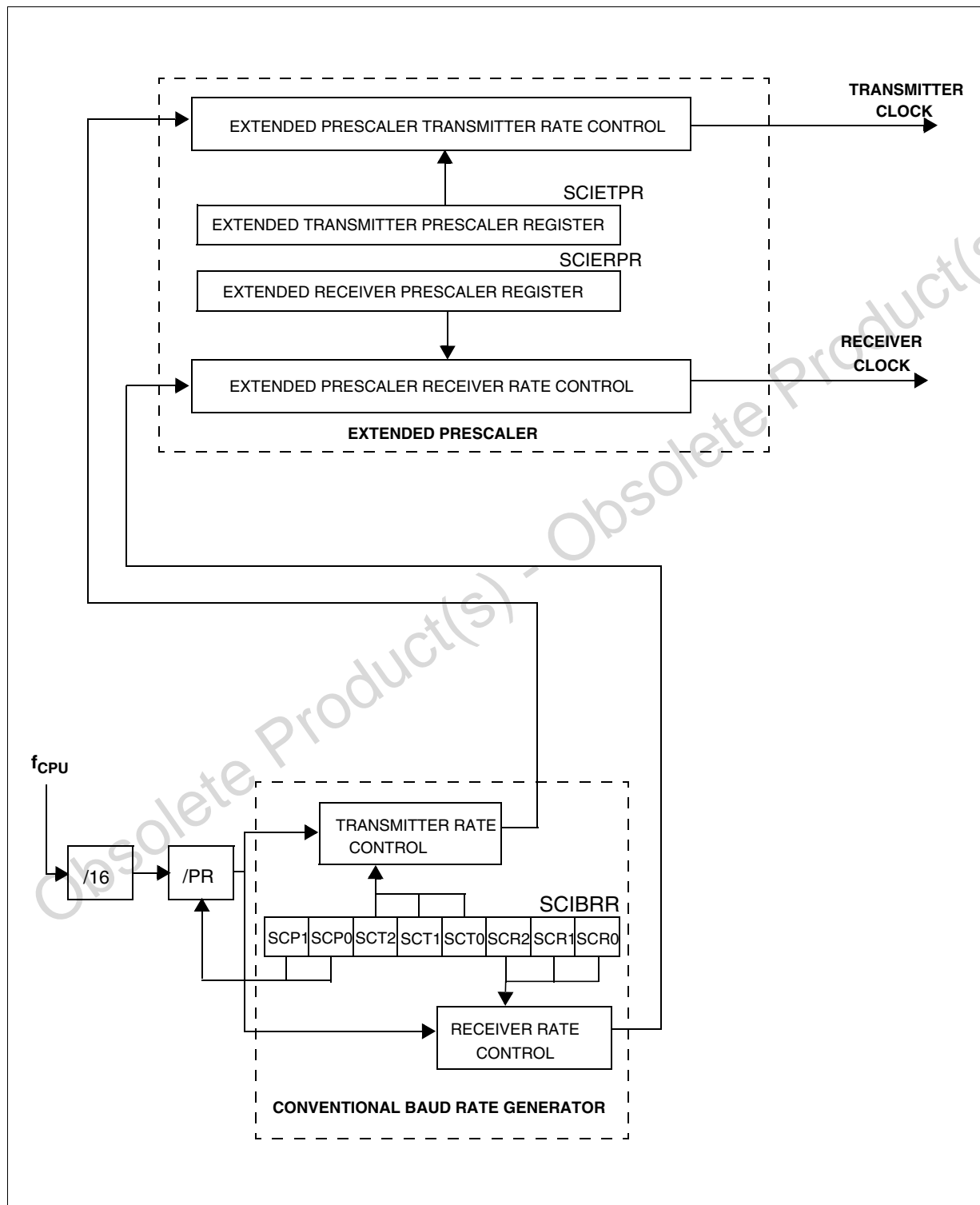
Transmission and reception are driven by their own baud rate generator.

Figure 47. Word Length Programming



SERIAL COMMUNICATIONS INTERFACE (Cont'd)

Figure 48. SCI Baud Rate and Extended Prescaler Block Diagram



SERIAL COMMUNICATIONS INTERFACE (Cont'd)**EXTENDED RECEIVE PRESCALER DIVISION REGISTER (SCIERP)**

Read/Write

Reset Value: 0000 0000 (00h)

Allows setting of the Extended Prescaler rate division factor for the receive circuit.

7							0
ERPR 7	ERPR 6	ERPR 5	ERPR 4	ERPR 3	ERPR 2	ERPR 1	ERPR 0

Bits 7:0 = **ERPR[7:0]** 8-bit Extended Receive Prescaler Register.

The extended Baud Rate Generator is activated when a value different from 00h is stored in this register. Therefore the clock frequency issued from the 16 divider (see [Figure 48](#)) is divided by the binary factor set in the SCIERP register (in the range 1 to 255).

The extended baud rate generator is not used after a reset.

EXTENDED TRANSMIT PRESCALER DIVISION REGISTER (SCIETPR)

Read/Write

Reset Value: 0000 0000 (00h)

Allows setting of the External Prescaler rate division factor for the transmit circuit.

7							0
ETPR 7	ETPR 6	ETPR 5	ETPR 4	ETPR 3	ETPR 2	ETPR 1	ETPR 0

Bits 7:0 = **ETPR[7:0]** 8-bit Extended Transmit Prescaler Register.

The extended Baud Rate Generator is activated when a value different from 00h is stored in this register. Therefore the clock frequency issued from the 16 divider (see [Figure 48](#)) is divided by the binary factor set in the SCIETPR register (in the range 1 to 255).

The extended baud rate generator is not used after a reset.

Table 21. Baudrate Selection

Symbol	Parameter	Conditions			Standard	Baud Rate	Unit
		f _{CPU}	Accuracy vs Standard	Prescaler			
f _{Tx} f _{Rx}	Communication frequency	8 MHz	~0.16%	Conventional Mode TR (or RR)=128, PR=13 TR (or RR)= 32, PR=13 TR (or RR)= 16, PR=13 TR (or RR)= 8, PR=13 TR (or RR)= 4, PR=13 TR (or RR)= 16, PR= 3 TR (or RR)= 2, PR=13 TR (or RR)= 1, PR=13	300 1200 2400 4800 9600 10400 19200 38400	~300.48 ~1201.92 ~2403.84 ~4807.69 ~9615.38 ~10416.67 ~19230.77 ~38461.54	Hz
			~0.79%	Extended Mode ETPR (or ERPR) = 35, TR (or RR)= 1, PR=1	14400	~14285.71	

USB INTERFACE (Cont'd)**DEVICE ADDRESS REGISTER (DADDR)**

Read / Write

Reset Value: 0000 0000 (00h)

7							0
0	ADD6	ADD5	ADD4	ADD3	ADD2	ADD1	ADD0

Bit 7 = Reserved. Forced by hardware to 0.

Bits 6:0 = **ADD[6:0]** Device address, 7 bits.

Software must write into this register the address sent by the host during enumeration.

Note: This register is also reset when a USB reset is received from the USB bus or forced through bit FRES in the CTLR register.**ENDPOINT n REGISTER A (EPnRA)**

Read / Write

Reset Value: 0000 xxxx (0xh)

7							0
ST_OUT	DTOG_TX	STAT_TX1	STAT_TX0	TBC 3	TBC 2	TBC 1	TBC 0

These registers (**EP0RA**, **EP1RA** and **EP2RA**) are used for controlling data transmission. They are also reset by the USB bus reset.**Note:** Endpoint 2 and the EP2RA register are not available on some devices (see device feature list and register map).Bit 7 = **ST_OUT** Status out.

This bit is set by software to indicate that a status out packet is expected: in this case, all nonzero OUT data transfers on the endpoint are STALLED instead of being ACKed. When ST_OUT is reset, OUT transactions can have any number of bytes, as needed.

Bit 6 = **DTOG_TX** Data Toggle, for transmission transfers.

It contains the required value of the toggle bit (0=DATA0, 1=DATA1) for the next transmitted data packet. This bit is set by hardware at the reception of a SETUP PID. DTOG_TX toggles only when the transmitter has received the ACK signal from the USB host. DTOG_TX and also DTOG_RX (see EPnRB) are normally updated by hardware, at the receipt of a relevant PID. They can be also written by software.

Bits 5:4 = **STAT_TX[1:0]** Status bits, for transmission transfers.

These bits contain the information about the endpoint status, which are listed below:

STAT_TX1	STAT_TX0	Meaning
0	0	DISABLED: transmission transfers cannot be executed.
0	1	STALL: the endpoint is stalled and all transmission requests result in a STALL handshake.
1	0	NAK: the endpoint is naked and all transmission requests result in a NAK handshake.
1	1	VALID: this endpoint is enabled for transmission.

These bits are written by software. Hardware sets the STAT_TX bits to NAK when a correct transfer has occurred (CTR=1) related to a IN or SETUP transaction addressed to this endpoint; this allows the software to prepare the next set of data to be transmitted.

Bits 3:0 = **TBC[3:0]** Transmit byte count for Endpoint n.

Before transmission, after filling the transmit buffer, software must write in the TBC field the transmit packet size expressed in bytes (in the range 0-8).

Warning: Any value outside the range 0-8 will induce undesired effects (such as continuous data transmission).

INSTRUCTION SET OVERVIEW (Cont'd)

11.2 INSTRUCTION GROUPS

The ST7 family devices use an Instruction Set consisting of 63 instructions. The instructions may

be subdivided into 13 main groups as illustrated in the following table:

Load and Transfer	LD	CLR						
Stack operation	PUSH	POP	RSP					
Increment/Decrement	INC	DEC						
Compare and Tests	CP	TNZ	BCP					
Logical operations	AND	OR	XOR	CPL	NEG			
Bit Operation	BSET	BRES						
Conditional Bit Test and Branch	BTJT	BTJF						
Arithmetic operations	ADC	ADD	SUB	SBC	MUL			
Shift and Rotates	SLL	SRL	SRA	RLC	RRC	SWAP	SLA	
Unconditional Jump or Call	JRA	JRT	JRF	JP	CALL	CALLR	NOP	RET
Conditional Branch	JRxx							
Interrupt management	TRAP	WFI	HALT	IRET				
Condition Code Flag modification	SIM	RIM	SCF	RCF				

Using a prebyte

The instructions are described with one to four opcodes.

In order to extend the number of available opcodes for an 8-bit CPU (256 opcodes), three different prebyte opcodes are defined. These prebytes modify the meaning of the instruction they precede.

The whole instruction becomes:

PC-2 End of previous instruction
PC-1 Prebyte
PC Opcode
PC+1 Additional word (0 to 2) according to the number of bytes required to compute the effective address

These prebytes enable instruction in Y as well as indirect addressing modes to be implemented. They precede the opcode of the instruction in X or the instruction using direct addressing mode. The prebytes are:

PDY 90 Replace an X based instruction using immediate, direct, indexed, or inherent addressing mode by a Y one.

PIX 92 Replace an instruction using direct, direct bit, or direct relative addressing mode to an instruction using the corresponding indirect addressing mode.

It also changes an instruction using X indexed addressing mode to an instruction using indirect X indexed addressing mode.

PIY 91 Replace an instruction using X indirect indexed addressing mode by a Y one.

12.2 ABSOLUTE MAXIMUM RATINGS

Stresses above those listed as “absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

tions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

12.2.1 Voltage Characteristics

Symbol	Ratings	Maximum value	Unit
V _{DD} - V _{SS}	Supply voltage	6.0	V
V _{DDA} - V _{SSA}	Analog Reference Voltage	6.0	
V _{IN} ^{1) & 2)}	Input voltage on true open drain pin	V _{SS} -0.3 to 6.0	
	Input voltage on any other pin	V _{SS} -0.3 to V _{DD} +0.3	
V _{ESD(HBM)}	Electrostatic discharge voltage (Human Body Model)	See “Electrostatic Discharge (ESD)” on page 109.	

12.2.2 Current Characteristics

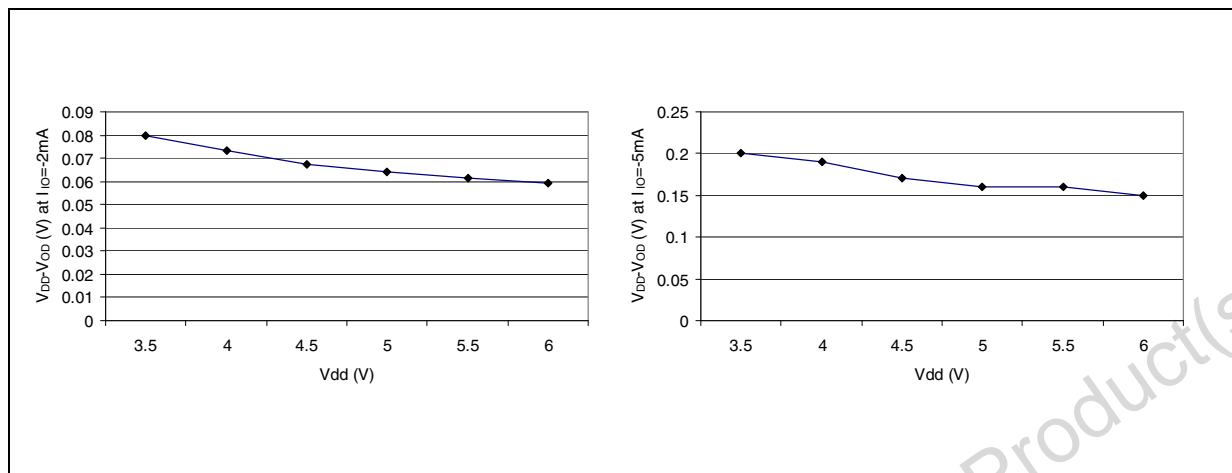
Symbol	Ratings	Maximum value	Unit
I_{VDD}	Total current into V_{DD} power lines (source) ³⁾	80	mA
I_{VSS}	Total current out of V_{SS} ground lines (sink) ³⁾	80	
I_{IO}	Output current sunk by any standard I/O and control pin	25	
	Output current sunk by any high sink I/O pin	50	
	Output current source by any I/Os and control pin	- 25	
$I_{INJ(PIN)}^{2) \& 4)}$	Injected current on V_{PP} pin	75	
	Injected current on \overline{RESET} pin	± 5	
	Injected current on OSCIN and OSCOUT pins	± 5	
	Injected current on PA0 to PA6 pins	± 5	
	Injected current on PA7 pin	+ 5	
	Injected current on any other pin ^{5) \& 6)}	± 5	
$\Sigma I_{INJ(PIN)}^{2)}$	Total injected current (sum of all I/O and control pins) ⁵⁾	± 20	

Notes:

1. Directly connecting the \overline{RESET} and I/O pins to V_{DD} or V_{SS} could damage the device if an unintentional internal reset is generated or an unexpected change of the I/O configuration occurs (for example, due to a corrupted program counter). To guarantee safe operation, this connection has to be done through a pull-up or pull-down resistor (typical: 4.7k Ω for \overline{RESET} , 10k Ω for I/Os). Unused I/O pins must be tied in the same way to V_{DD} or V_{SS} according to their reset configuration.
2. $I_{INJ(PIN)}$ must never be exceeded. This is implicitly insured if V_{IN} maximum is respected. If V_{IN} maximum cannot be respected, the injection current must be limited externally to the $I_{INJ(PIN)}$ value. A positive injection is induced by $V_{IN} > V_{DD}$ while a negative injection is induced by $V_{IN} < V_{SS}$. For true open-drain pads, there is no positive injection current, and the corresponding V_{IN} maximum must always be respected.
3. All power (V_{DD}) and ground (V_{SS}) lines must always be connected to the external supply.
4. Negative injection disturbs the analog performance of the device. In particular, it induces leakage currents throughout the device including the analog inputs. To avoid undesirable effects on the analog functions, care must be taken:
 - Analog input pins must have a negative injection less than 0.8 mA (assuming that the impedance of the analog voltage is lower than the specified limits)
 - Pure digital pins must have a negative injection less than 1.6mA. In addition, it is recommended to inject the current as far as possible from the analog input pins.
5. When several inputs are submitted to a current injection, the maximum $\Sigma I_{INJ(PIN)}$ is the absolute sum of the positive and negative injected currents (instantaneous values). These results are based on characterization with $\Sigma I_{INJ(PIN)}$ maximum current injection on four I/O port pins of the device.
6. True open drain I/O port pins do not accept positive injection.

I/O PORT PIN CHARACTERISTICS (Cont'd)

Figure 71. Typical V_{DD} - V_{OH} vs. V_{DD} (high sink port)



12.9 CONTROL PIN CHARACTERISTICS

12.9.1 Asynchronous $\overline{\text{RESET}}$ Pin

Subject to general operating conditions for V_{DD} , f_{CPU} , and T_A unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ ¹⁾	Max	Unit
V_{IH}	Input High Level Voltage		$0.7 \times V_{DD}$		V_{DD}	V
V_{IL}	Input Low Voltage		V_{SS}		$0.3 \times V_{DD}$	V
V_{hys}	Schmitt trigger voltage hysteresis ³⁾			400		mV
V_{OL}	Output low level voltage ⁴⁾ (see Figure 73, Figure 74)	$V_{DD}=5\text{V}$	$I_{IO}=5\text{mA}$		1 ²⁾	V
			$I_{IO}=2\text{mA}$		0.4 ²⁾	
R_{ON}	Weak pull-up equivalent resistor ⁵⁾	$V_{IN}=V_{SS}$		60		k Ω
$t_{w(RSTL)out}$	Generated reset pulse duration	External pin or internal reset sources		6 30		1/ f_{SFOSC} μs
$t_{h(RSTL)in}$	External reset pulse hold time ⁶⁾		10			μs

Notes:

1. Unless otherwise specified, typical data are based on $T_A=25^\circ\text{C}$ and $V_{DD}=5\text{V}$, not tested in production.
2. Data guaranteed by design.
3. Hysteresis voltage between Schmitt trigger switching levels. Based on characterization results, not tested.
4. The I_{IO} current sunk must always respect the absolute maximum rating specified in Section 12.2 and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VSS} .
5. The R_{ON} pull-up equivalent resistor is based on a resistive transistor (corresponding I_{ON} current characteristics described in Figure 72). This data is based on characterization results, not tested in production.
6. To guarantee the reset of the device, a minimum pulse has to be applied to $\overline{\text{RESET}}$ pin. All short pulses applied on $\overline{\text{RESET}}$ pin with a duration below $t_{h(RSTL)in}$ can be ignored.

CONTROL PIN CHARACTERISTICS (Cont'd)

Figure 75. $\overline{\text{RESET}}$ pin protection when LVD is enabled. ¹⁾²⁾³⁾⁴⁾

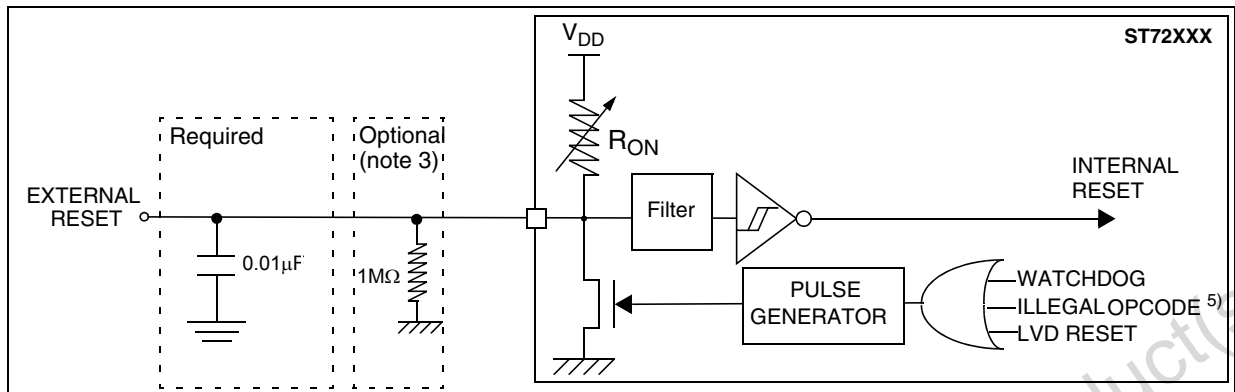
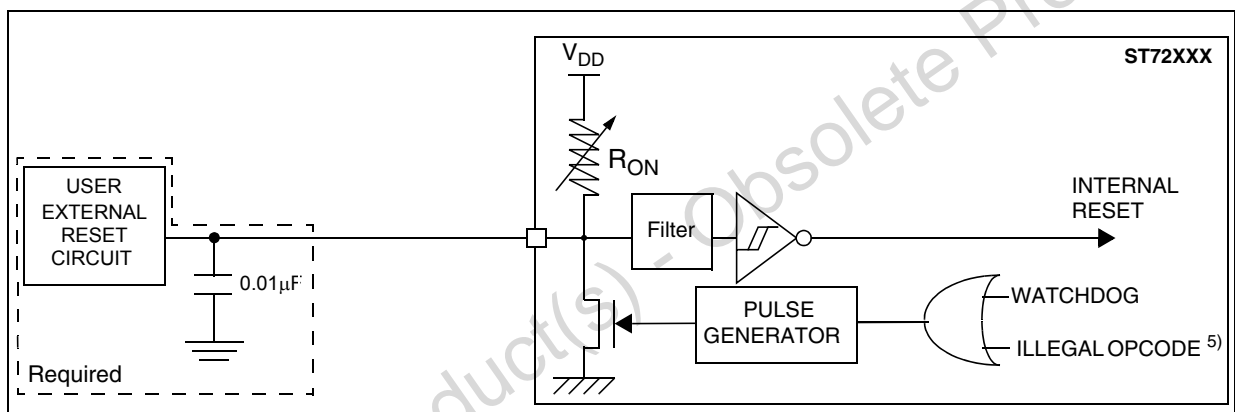


Figure 76. $\overline{\text{RESET}}$ pin protection when LVD is disabled. ¹⁾



Note 1:

- The reset network protects the device against parasitic resets.
- The output of the external reset circuit must have an open-drain output to drive the ST7 reset pad. Otherwise the device can be damaged when the ST7 generates an internal reset (LVD or watchdog).
- Whatever the reset source is (internal or external), the user must ensure that the level on the $\overline{\text{RESET}}$ pin can go below the V_{IL} max. level specified in [section 12.9.1 on page 113](#). Otherwise the reset will not be taken into account internally.
- Because the reset circuit is designed to allow the internal RESET to be output in the $\overline{\text{RESET}}$ pin, the user must ensure that the current sunk on the RESET pin is less than the absolute maximum value specified for $I_{INJ}(\text{RESET})$ in [section 12.2.2 on page 102](#).

Note 2: When the LVD is enabled, it is recommended not to connect a pull-up resistor or capacitor. A 10nF pull-down capacitor is required to filter noise on the reset line.

Note 3: In case a capacitive power supply is used, it is recommended to connect a 1MΩ pull-down resistor to the $\overline{\text{RESET}}$ pin to discharge any residual voltage induced by the capacitive effect of the power supply (this will add 5µA to the power consumption of the MCU).

Note 4: Tips when using the LVD:

1. Check that all recommendations related to the reset circuit have been applied (see notes above).
2. Check that the power supply is properly decoupled (100nF + 10µF close to the MCU). Refer to AN1709 and AN2017. If this cannot be done, it is recommended to put a 100nF + 1MΩ pull-down on the RESET pin.
3. The capacitors connected on the RESET pin and also the power supply are key to avoid any start-up marginality. In most cases, steps 1 and 2 above are sufficient for a robust solution. Otherwise: replace 10nF pull-down on the RESET pin with a 5µF to 20µF capacitor."

ADC CHARACTERISTICS (Cont'd)

12.12.1 ADC Accuracy

Table 27. $f_{CPU}=8\text{ MHz}$, $f_{ADC}=4\text{ MHz}$ $R_{AIN}<10\text{k}\Omega$ ²⁾

Symbol	Parameter	Conditions	Typ	Max ¹⁾	Unit
$ E_T $	Total unadjusted error	$V_{DD}=4\text{V}-5.5\text{V}$	3		LSB
$ E_O $	Offset error		1	2	
$ E_G $	Gain Error		0.7	2	
$ E_D $	Differential linearity error		1.3	2	
$ E_L $	Integral linearity error		2.9	5	

Notes:

1. Not tested in production, guaranteed by characterization. All accuracy measurements are taken with the MCU in WAIT mode (no I/O switching) and when adequate low-pass filtering is present (0.1 μF capacitor between V_{DD}/V_{DDA} and V_{SS}/V_{SSA}). Outside these conditions, a degree of microcontroller noise may result, causing accuracy errors which will vary based on board layout and the type of CPU activity.

2. ADC Accuracy vs. Negative Injection Current:

Injecting negative current on any of the analog input pins significantly reduces the accuracy of the conversion being performed on another analog input.

For $I_{INJ}=-0.8\text{mA}$, the typical leakage induced inside the die is 1.6 μA and the effect on the ADC accuracy is a loss of 4 LSB for each 10K Ω increase of the external analog source impedance. It is recommended to add a Schottky diode (pin to ground) to analog pins which may potentially inject negative current. Any positive injection current within the limits specified for $I_{INJ}(\text{PIN})$ and $\Sigma I_{INJ}(\text{PIN})$ in [Section 12.8](#) does not affect the ADC accuracy.

Figure 89. 32-Pin Plastic Dual In-Line Package, Shrink 400-mil Width

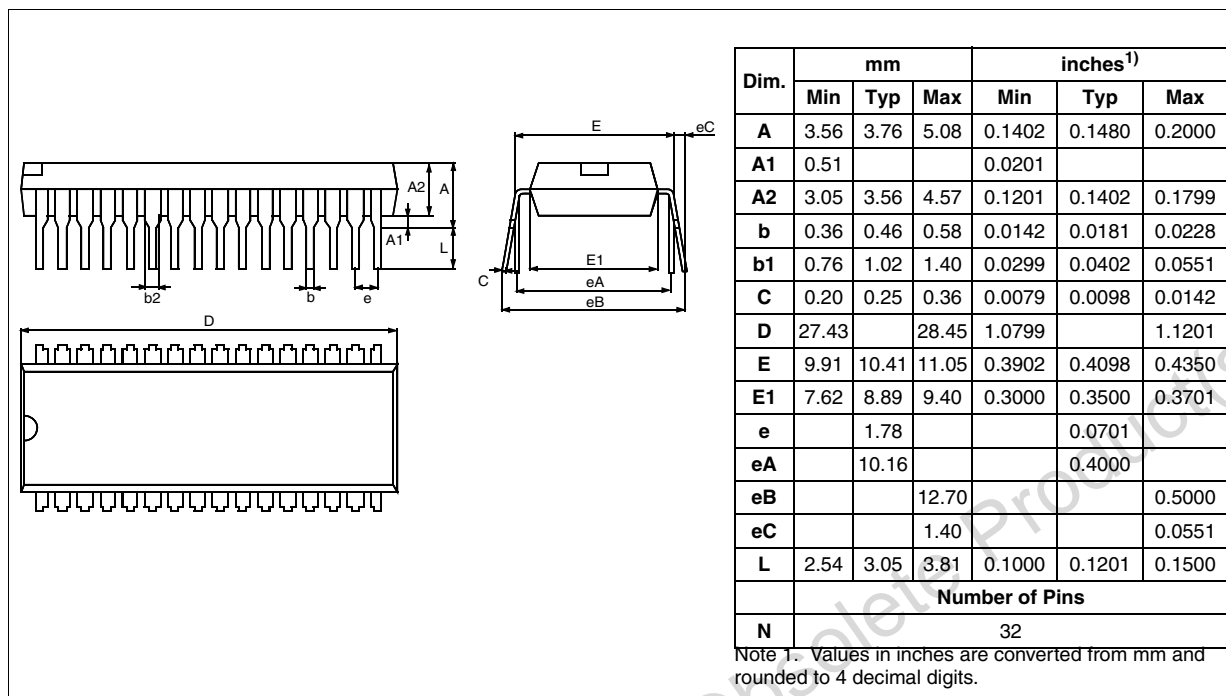
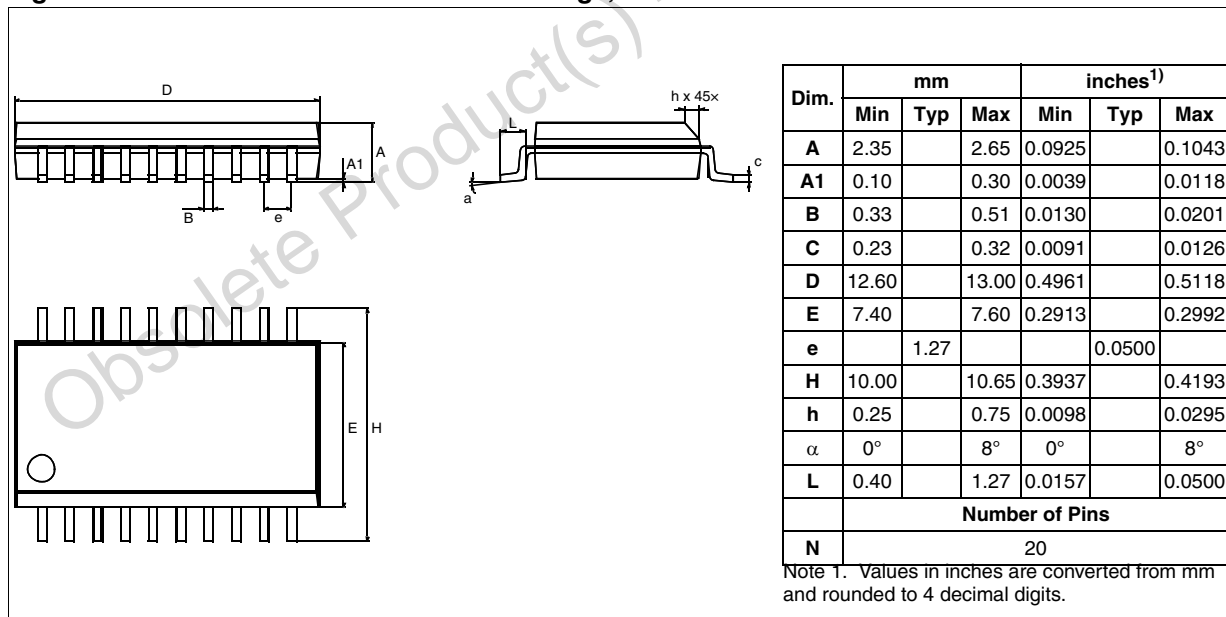


Figure 90. 20-Pin Plastic Small Outline Package, 300-mil Width



14 DEVICE CONFIGURATION AND ORDERING INFORMATION

Each device is available for production in user programmable versions (FLASH) as well as in factory coded versions (ROM).

ST7262 devices are ROM versions.

ST72F62 FLASH devices are shipped to customers with a default content (FFh). This implies that FLASH devices have to be configured by the customer using the Option Byte while the ROM devices are factory-configured.

14.1 OPTION BYTE

The Option Byte allows the hardware configuration of the microcontroller to be selected.

The Option Byte has no address in the memory map and can be accessed only in programming mode using a standard ST7 programming tool. The default content of the FLASH is fixed to FFh. This means that all the options have “1” as their default value.

7							0
-	-	WDG SW	NEST	LVD	-	OSC 12/6	FMP_ R

Bits 7:6 = Reserved.

Bit 5 = **WDGSW** *Hardware or software watchdog*

This option bit selects the watchdog type.

0: Hardware enabled

1: Software enabled

Bit 4 = **NEST**

14.2 DEVICE ORDERING INFORMATION AND TRANSFER OF CUSTOMER CODE

Customer code is made up of the ROM contents and the list of the selected options (if any). The ROM contents are to be sent on diskette, or by electronic means, with the hexadecimal file in .S19 format generated by the development tool. All unused bytes must be set to FFh.

This option bit selects the nested interrupts feature.

0: Nested interrupt feature disabled

1: Nested interrupt feature enabled

Bit 3 = **LVD** *Low Voltage Detector selection*

This option bit selects the LVD.

0: LVD enabled

1: LVD disabled

Bit 2= Reserved.

Bit 1 = **OSC12/6** *Oscillator selection*

This option bit selects the clock divider used to drive the USB interface at 6MHz.

0: 6 MHz oscillator (no divider for USB)

1: 12 Mhz oscillator (2 divider for USB)

Bit 0 = **FMP_R** *Memory Readout Protection*

Readout protection, when selected provides a protection against program memory content extraction and against write access to Flash memory. Erasing the option bytes when the FMP_R option is selected will cause the whole memory to be erased first and the device can be reprogrammed. Refer to the ST7 Flash Programming Reference Manual and [section 4.3.1 on page 14](#) for more details.

0: Read-out protection enabled

1: Read-out protection disabled

The selected options are communicated to STMicroelectronics using the correctly completed OPTION LIST appended.

Refer to application note AN1635 for information on the counter listing returned by ST after code has been transferred.

The STMicroelectronics Sales Organization will be pleased to provide detailed information on contractual points.